19-5707; Rev 0; 12/10

EVALUATION KIT AVAILABLE



## Dual DisplayPort Graphics Multiplexer with HDMI Level Shifter

### **General Description**

The MAX14886 high-speed, low-skew, active redriver

multiplexer is ideal for switching between outputs of

dual-graphics systems and signal conditioning to meet

HDMI<sup>™</sup> v.1.4 compliance up to 2.25Gbps at an external

HDMI connector. It is used for switching between inte-

grated (e.g., Intel or AMD) and discrete graphics (e.g., NVIDIA or ATI GPU). The device is VESA DisplayPort™

Interoperability Guideline v.1.1a-compliant (requires

external DDC logic) and integrates seamlessly with an

The device accommodates differential inputs as low

as 200mV and drives transition minimized differential

signaling (TMDS®) outputs to 1000mV (typ). A precision

resistor on the output level adjust pin (ADJ) allows differ-

entiated output back-termination resistors of  $400\Omega$  (typ) to better meet HDMI mask jitter compliance, while main-

taining full TMDS swing requirements. The device supports AC-(DisplayPort) or DC-(HDMI) coupling directly to the graphics IC and must be DC-coupled to the HDMI connector. In addition, the device features current back-

flow protection at the HDMI connector and a low-power,

The device operates with a single +3.3V supply, is specified over the 0°C to +70°C commercial temperature

range, and is available in a 5mm x 5mm, 40-pin TQFN

**Dual Graphics Notebook Computers** 

Switches or Adapters

Dual Mode DisplayPort to HDMI External

**Applications** 

active-high or active-low shutdown mode.

external HDMI connector on the motherboard.

Fea

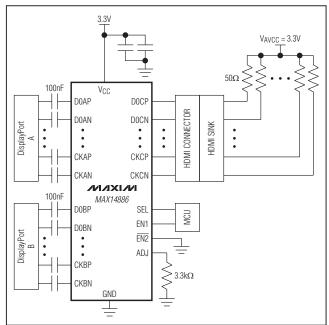
- Single +3.3V Supply
  Meets HDMI v.1.4 Eye Mask Up to 2.25Gbps
- Meets VESA DisplayPort Interoperability Guideline v.1.1a (Requires External DDC Logic)
- Low-Power Shutdown Mode Active High or Active Low
- Output Level Adjust (ADJ) for Output Back-Termination Without Amplitude Loss
- Seamless Integration into Dual-Graphics Systems
   with External HDMI Connector
  - DC-Coupled HDMI Outputs Mate Directly to HDMI Connector AC- or DC-Coupled TMDS-Formatted Inputs

## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX14886CTL+	0°C to +70°C	40 TQFN-EP*

+Denotes a lead(Pb)-free/RoHS-compliant package. \*EP = Exposed pad.

## **Typical Operating Circuit**



HDMI is a trademark of HDMI Licensing, LLC.

DisplayPort is a trademark of Video Electronics Standards Association (VESA).

TMDS is a registered trademark of Silicon Image, Inc.

### 

package.

Maxim Integrated Products 1

Features Features 25Gbps illity Guideline ) t Back-

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

#### **ABSOLUTE MAXIMUM RATINGS**

(Voltages referenced to GND.)

· · · · · · · · · · · · · · · · · · ·	
Vcc	0.3V to +4.0V
EN1, EN2, SEL, ADJ	0.3V to (VCC + 0.3V)
D_CP, D_CN, CKCP, CKCN Short-Circ	cuit
Output Current	±30mA
All Other Pins Short-Circuit Current	±5mA
Continuous Power Dissipation (TA = +	70°C)
TQFN (derate 35.7mW/°C above +7	0°C)2857mW

Operating Temperature Range	0°C to +70°C
Storage Temperature Range	65°C to +150°C
Maximum Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

### PACKAGE THERMAL CHARACTERISTICS (Note 1)

TOFN

MAX14886

Junction-to-Ambient Thermal Resistance (0JA) .......45°C/W 

Note 1: Package thermal resistances were obtained using method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +3.3V, T_A = 0^{\circ}C \text{ to } +70^{\circ}C, R_{ADJ} = 3.3k\Omega, C_{CL} = 100nF, typical values are at T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC PERFORMANCE		·				
Supply Voltage	Vcc		3		3.6	V
Supply Current	Icc	$EN1 = high, \overline{EN2} = low$			52.5	mA
Total Supply Current	Ignd	$50\Omega$ termination to AVCC, V <sub>AVCC</sub> = +3.3V (Note 3)			105	mA
Shutdown Supply Current	ISHUT	$EN1 = low \text{ or } \overline{EN2} = high$			100	μA
Single-Ended Input Termination Resistance	R <sub>IN</sub>	DC	40		60	Ω
Single-Ended Output Voltage High	VOH	DC, V <sub>AVCC</sub> = +3.3V (Notes 3, 4)	VAVCC - 0.01		VAVCC + 0.01	V
Single-Ended Output Voltage Low	V <sub>OL</sub>	DC, V <sub>AVCC</sub> = +3.3V (Notes 3, 4)	VAVCC - 0.6		Vavcc - 0.45	V

### **ELECTRICAL CHARACTERISTICS (continued)**

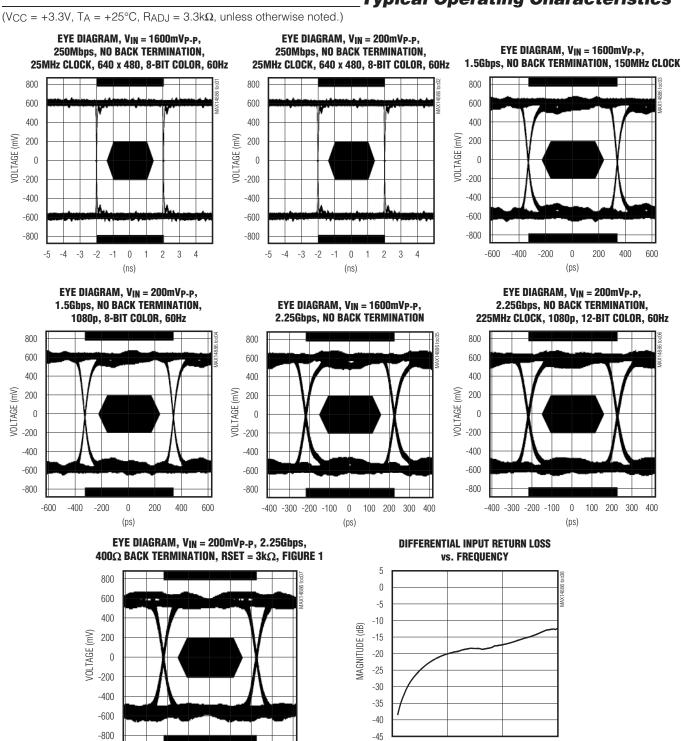
 $(V_{CC} = +3.3V, T_{A} = 0^{\circ}C$  to  $+70^{\circ}C, R_{ADJ} = 3.3k\Omega, C_{CL} = 100nF$ , typical values are at T<sub>A</sub> =  $+25^{\circ}C$ .) (Note 2)

			[			
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
AC PERFORMANCE						
Differential Input Return Loss	SDD11	$150MHz \le f \le 1.25GHz$			-8	dB
Input Fraguanay Danga	fini	Clock	25		225	MHz
Input Frequency Range	fIN	Data	225		1125	
Differential Input Range	VIDIFF		200		1600	mV
Differential Output Voltage	Vodiff	50 $\Omega$ single termination	900		1250	mV
Output Rise/Fall Time	t <sub>R/F</sub>	20% to 80%, 2.25Gbps			80	ps
Deterministic Jitter	tDJ	K28.5 pattern, up to 2.25Gbps (Note 4)			0.04	UI
Random Jitter	t <sub>RJ</sub>	D10.2 pattern, 2.25Gbps (Note 4)			1.1	psrms
Lane-to-Lane Skew	tsk			50		ps
Propagation Delay	tpD			250		ps
CONTROL LOGIC (EN1, EN2, S	EL)		·			
Input Logic-Low Voltage	VIL				0.6	V
Input Logic-High Voltage	Vih		1.4			V
Input Logic Hysteresis	VHYST			50		mV
Input Pulldown/Pullup Resistor	RIPULL			400		kΩ
Shutdown Recovery Time	tSHUT			20		μs
TMDS Mux Switching Time	tMUX			50		ns
ESD PROTECTION						
All Pins		Human Body Model		±8		kV

Note 2: All units are production tested at TA = +70°C. Specifications over temperature are guaranteed by design.

Note 3: AVCC is an external supply.

Note 4: Guaranteed by design; not production tested.



0

1

FREQUENCY (GHz)

2

3

### **Typical Operating Characteristics**

MAX14886

-400 -300 -200 -100

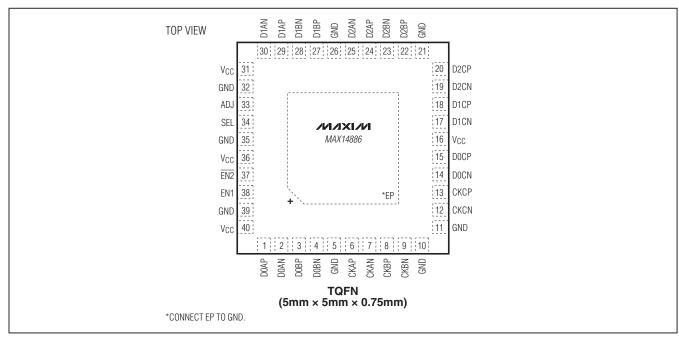
0

(ps)

100 200 300 400

### **Pin Configuration**

**MAX14886** 



PIN	NAME	FUNCTION
1	DOAP	Noninverting Input D0 for Channel A
2	DOAN	Inverting Input D0 for Channel A
3	DOBP	Noninverting Input D0 for Channel B
4	DOBN	Inverting Input D0 for Channel B
5, 10, 11, 21, 26, 32, 35, 39	GND	Ground
6	CKAP	Noninverting Input Clock for Channel A
7	CKAN	Inverting Input Clock for Channel A
8	СКВР	Noninverting Input Clock for Channel B
9	CKBN	Inverting Input Clock for Channel B
12	CKCN	Inverting Output Clock
13	CKCP	Noninverting Output Clock
14	DOCN	Inverting Output D0
15	DOCP	Noninverting Output D0
16, 31, 36, 40	VCC 1.4 / UE ceramic capacitors in paralle	
17	D1CN	Inverting Output D1

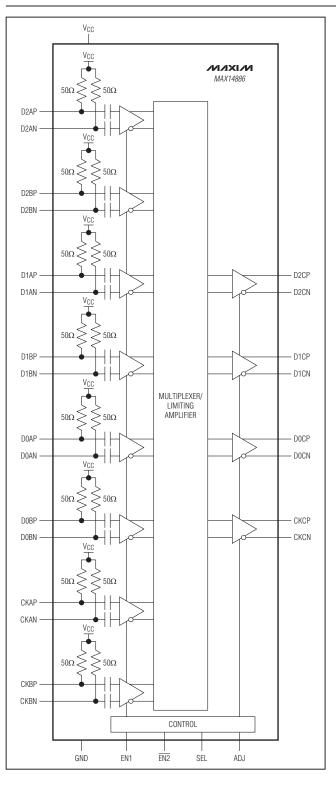
			•
iel B	22	D2BP	Noninverting Ir
	23	D2BN	Inverting Input
	24	D2AP	Noninverting Ir
	25	D2AN	Inverting Input
	27	D1BP	Noninverting Ir
Channel A	28	D1BN	Inverting Input
annel A	29	D1AP	Noninverting Ir
Channel B	30	D1AN	Inverting Input
annel B	33	ADJ	Output Level A
	34	SEL	Mux Select Inp pulled down b
ass VCC	37	EN2	Active-Low En nally pulled up resistor.
and parallel			Active-High Er

#### **Pin Description**

PIN	NAME	FUNCTION
18	D1CP	Noninverting Output D1
19	D2CN	Inverting Output D2
20	D2CP	Noninverting Output D2
22	D2BP	Noninverting Input D2 for Channel B
23	D2BN	Inverting Input D2 for Channel B
24	D2AP	Noninverting Input D2 for Channel A
25	D2AN	Inverting Input D2 for Channel A
27	D1BP	Noninverting Input D1 for Channel B
28	D1BN	Inverting Input D1 for Channel B
29	D1AP	Noninverting Input D1 for Channel A
30	D1AN	Inverting Input D1 for Channel A
33	ADJ	Output Level Adjust
34	SEL	Mux Select Input. SEL is internally pulled down by a 400k $\Omega$ (typ) resistor.
37	EN2	Active-Low Enable Input. $\overline{\text{EN2}}$ is internally pulled up by a 400k $\Omega$ (typ) resistor.
38	EN1	Active-High Enable Input. EN1 is internally pulled down by a 400k $\Omega$ (typ) resistor.
	EP	Exposed Pad. Connect EP to GND.

### M/IXI/M

MAX14886



### Functional Diagram/Truth Tables

EN1	EN2	FUNCTION
0/Unconnected	Х	Shutdown
Х	1/Unconnected	Shutdown
1	0	Active

X = Don't care.

SEL	D_A_, CKA_	D_B_, CKB_
0/Unconnected	On	Off
1	Off	On

X = Don't care.

#### **Detailed Description**

The MAX14886 is a high-speed, low-skew, active redriver multiplexer designed to switch and amplify TMDS-formatted signals. Input buffers have  $50\Omega$  HDMI-compliant terminations to V<sub>CC</sub> (see the *Functional Diagram/Truth Tables*), allowing either DC-coupling to an HDMI source or AC-coupling to a DisplayPort source. Signals from the input buffers are multiplexed and redriven by the limiting amplifier and an open-collector output buffer. The HDMI monitor sink is DC-coupled to the outputs and provides DC bias.

Both TMDS clock and data are multiplexed and redriven to full HDMI v.1.4 levels with low skew and jitter to guarantee mask compliance at an external HDMI connector. The device is VESA DisplayPort Interoperability Guideline v.1.1a-compliant and integrates seamlessly with an external HDMI connector on the motherboard. The low-frequency signals (DDC, CEC, and HPD) can be handled by external low-cost logic.

The device accommodates differential inputs as low as 200mV and drives differential TMDS outputs to 1000mV (typ). A precision resistor on the output level adjust pin (ADJ) allows differential output back-termination resistors of 400 $\Omega$  (typ) to better meet HDMI mask jitter compliance, while maintaining full TMDS swing requirements.

This device also features both active-high and activelow enable inputs. One of the enable inputs can be connected to either V<sub>CC</sub> or GND, while the other can be used to control the device (see the *Functional Diagram/ Truth Tables* and *Enable Inputs (EN1, EN2)* section). This eliminates any issues with logic sense and the need for an inverter.

#### Level Translation

The device accepts two sets of four differential DisplayPort-level TMDS-formatted inputs, each with magnitudes as low as 200mV. The selected channel is translated to full HDMI TMDS levels that are HDMI v.1.4 port mask-compliant up to 2.25Gbps.

#### Enable Inputs (EN1, EN2)

The device features both an active-high enable input (EN1) and an active-low enable input (EN2) that can be controlled by LVCMOS or LVTTL. EN1 has an internal 400k $\Omega$  (typ) pulldown resistor, and EN2 has an internal 400k $\Omega$  (typ) pullup resistor. When EN1 is driven low or left unconnected, or EN2 is driven high or left unconnected, the device enters low-power shutdown mode. For normal operation drive both EN1 high and EN2 low. See the *Functional Diagram/Truth Tables*.

Only one input is necessary to control the device. If active-high enable is desired, connect  $\overline{\text{EN2}}$  to GND and use EN1 to control the device. Similarly, for active-low enable, connect EN1 to V<sub>CC</sub> and use  $\overline{\text{EN2}}$  to control the device.

**Note:** The monitor sink termination must be present and powered before enabling the device (see the *Control Sequence* section and Figure 2).

#### **Digital Control Input (SEL)**

The device provides two sets of 4 channels for all the differential signals required by HDMI connections. The SEL input controls which channel is translated to the output channel (see the *Functional Diagram/Truth Tables*). An internal 400k $\Omega$  pulldown resistor guarantees that channel A is translated to the output if the SEL pin is not externally driven.

#### **Output Level Adjust (ADJ)**

The level-shifter's output current and output signal swing are set with an external  $\pm 1\%$  precision  $3.3k\Omega$  (typ) resistor. If a double output termination ( $400\Omega$  typ) is desired for signal integrity reasons, the ADJ resistor value can be decreased to maintain a desired output swing (Figure 1).

#### **Applications Information**

#### **HDMI** Driver

The device's high-speed, low-skew, active redriver multiplexer is ideal for switching between outputs of dual-graphics systems and signal conditioning to meet HDMI v.1.4 compliance at an external HDMI connector (Figure 1). It is well suited for switching between integrated (e.g., Intel or AMD) and discrete graphics (e.g., NVIDIA or ATI GPU). The device is VESA DisplayPort Interoperability Guideline v.1.1a-compliant (requires external DDC logic) and integrates seamlessly with an external HDMI connector on the motherboard.

#### **Output Termination**

Outputs are terminated in normal use by the HDMI monitor. For  $50\Omega$  test equipment purposes, terminate each output with a high-frequency bias-T that has an inductor in series with a  $50\Omega$  resistor to VCC.

#### **Control Sequence**

The monitor sink termination must be present and powered before enabling the device. A simple circuit can be added to protect the device by forcing hot-plug detection (HPD) to be present before the part is enabled (Figure 2).



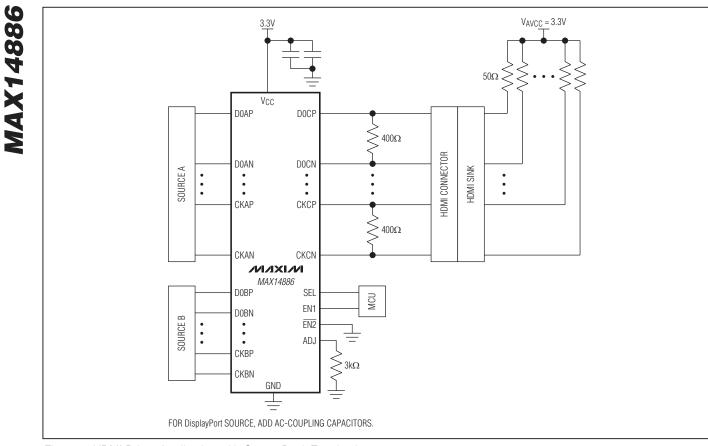


Figure 1. HDMI Driver Application with Output Back Termination

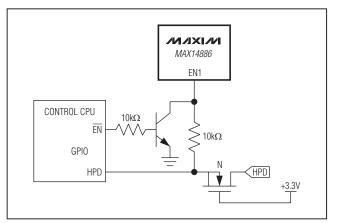


Figure 2. Control Sequence Protection Circuit

#### **Power-Supply Bypassing**

Adequate power-supply bypassing is necessary to maximize performance and noise immunity. Bypass each VCC pin to GND with high-frequency, low-ESR, X7R/X5R 10nF and  $4.7\mu$ F surface-mount ceramic capacitors as close as possible to the device.

#### **Printed Circuit Board (PCB) Traces**

Input and output trace characteristics affect the performance of the device. Connect each of the inputs and outputs to a 50 $\Omega$  characteristic impedance trace in to minimize reflections. Avoid discontinuities in differential impedance and maximize common-mode noise immunity by maintaining the distance between differential traces and avoiding sharp corners. Minimize the number of vias to prevent impedance discontinuities. Reduce reflections by maintaining the 50 $\Omega$  characteristic impedance through connectors and across cables. Minimize skew by matching the electrical length of the traces.



#### **Exposed-Pad Package**

The exposed-pad, 40-pin TQFN package incorporates features that provide a very low thermal resistance path for heat removal from the IC. The exposed pad on the device must be soldered to the circuit board ground plane for proper electrical and thermal performance. For more information on exposed-pad packages, refer to Application Note 862: *HFAN-08.1: Thermal Considerations of QFN and Other Exposed-Paddle Packages.* 

### PROCESS: BICMOS

### **Package Information**

**Chip Information** 

For the latest package outline information and land patterns (footprints), go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
40 TQFN-EP	T4055+2	<u>21-0140</u>	<u>90-0002</u>

**Revision History** 

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	12/10	Initial release	_

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

 $\_$  Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600

© 2010 Maxim Integrated Products

Maxim is a registered trademark of Maxim Integrated Products, Inc.